



Response Under 37 CFR §1.116
Expedited Procedure
Group Art Unit 1765

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up
11/30/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

ITO et al.

Group Art Unit: 1765

E/A

L.J.M.-E

12/1/2001

Appln. No.: 09/361,980

Examiner: L. Umez-Eronini

Filed: July 28, 1999

Title: METHOD OF ETCHING METALLIC THIN
FILM ON THIN FILM RESISTOR

RECEIVED
NOV 30 2001
TC 1700

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November 27, 2001

AMENDMENT

Hon. Commissioner of Patents
Box AF
Washington, D.C. 20231

Sir:

In reply to the Final Office Action dated August 27, 2001, please enter the following
amendments and remarks:

IN THE CLAIMS:

Please cancel claim 30 without prejudice or disclaimer and amend claim 19 as
follows:

19. (Twice Amended) A method of etching a metallic film, comprising the steps
of:
forming a thin film resistor on a semiconductor substrate through an insulation layer
interposed therebetween;

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E,
Bx